



Ball-Wedge Bonder 5310

Bond System

| | |
|-------------------|---|
| Wire types | Gold wire 17,5-50µm on 2" spool |
| Bondhead | Ball-Wedge for Gold wire Standard capillaries 16mm (optional 19mm) |
| Ultrasonic System | F&S Generator 67kHz (optional 100, 120, 140kHz) |

Bonder Base

Axes

- Programmable linear Z-axis with 60mm stroke
- Step resolution: 1 µm
- Standard working height: 55 mm
- Manipulator in X and Y: 18x18 mm
- Equivalent to: 1: 7

Hardware

- Stepper motor driven Z-linear axis,
- Single-board PC, coin-guided teach-in,
- Internal hard disk, operation and menu-guided via shuttle wheel with confirmation button

Software

- Programmable single Bonds
- Loop shapes can be saved

Control Manual

Dimensions W x D x H – 63 x 58 x 40 cm, weight approx. 30kg

Connections 100-230 VAC, 1 Phase, 50/60 Hz, max 230 VA
Ø 6mm standard-vacuum tubing

Heater controller Integrated in the machine 0-250 °C

The 53xx Series:

The Gold-Ball-Bonder 5310 can process gold wires from 17,5 to 50 µm, using the bumping mode as well as the stitchbond mode .

Due to the motor driven Z-axis you work always with repeatable results. Additionally every parameter can be saved to the internal harddisk.

You always work with repeatable results – also after a lot of years. The handling, supported by a colour display and the input with an shuttle-wheel make the programming of the machine very easy. The operator can create different kinds of loops with the manipulator system. Operators require only a minimum of training, making the 5310 manual ball bonder the ideal choice for prototype, re-work and smallscale production.

The 5310 is perfect suited for complex bond- tasks, optimal quality and the most favourable price. This machine is the right choice for such applications.

Workholder

Standard-Workholder
with mechanical clamping
Ø80mm



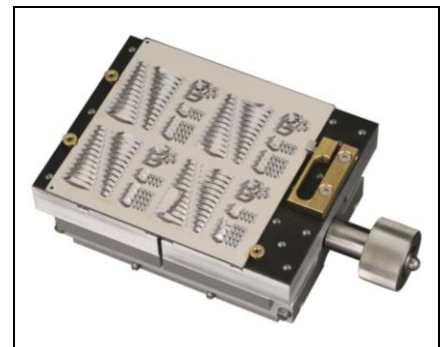
Optional:



workholder for parts up to 4x4"
with vacuum and mechanical
clamping



TO workholder with
mechanical clamping



4x4" workholder with
rubbered surface and
mechanical clamping

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